

FEATURES/BENEFITS

- 5V tolerant inputs and outputs
- Industry standard pinouts
- 25Ω Series resistor for low switching noise
- Bus Hold feature holds last active state during 3-state operation
- $10\mu A$ I_{CCQ} quiescent power supply current
- Hot insertable
- 2.0V – 3.6V V_{CC} supply operation
- $\pm 12mA$ balanced output drive
- Meets or exceeds JEDEC Standard 36 specifications
- $t_{PD} = 6.0ns$ (transparent mode)
- Input hysteresis for noise immunity
- Multiple power and ground pins for low noise
- Operating temperature range:
–40°C to 85°C
- Latch-up performance exceeds 500mA
- ESD performance:
Human body model > 2000V
Machine model > 200V
- Packages available:
56-pin TSSOP
56-pin SSOP

DESCRIPTION

The LCX162H543 is a 16-bit latched bus transceiver with three-state outputs that is ideal for driving address and data buses. Two independent 8-bit D-type latched transceivers are used with separate input and output control to permit independent control of data flow in either direction. The QS74LCX162H543 with integrated output resistor is ideally suited for low noise environments where reduced output overshoot and undershoot are critical requirements. Bus Hold circuitry on the data inputs retains the last active state during 3-state operation, eliminating the need for external pull-up resistors. The 3.3VLCXPlus family features low power, low switching noise, and fast switching speeds for low power portable applications as well as high-end advanced workstation applications. 5V tolerant inputs and outputs allow this LCXPlus product to be used in mixed 5V and 3.3V applications. Easy board layout is facilitated by the use of flow-through pinouts and byte enable controls provide architectural flexibility for systems designers. To accommodate hot-plug or live insertion applications, this product is designed not to load an active bus when V_{CC} is removed.

Figure 1. Functional Block Diagram

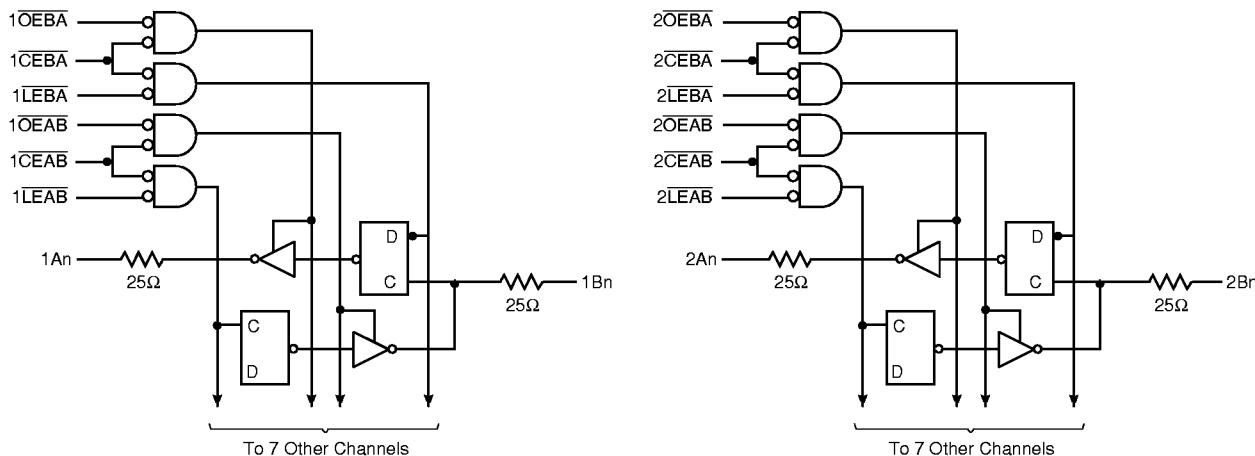


Figure 2. Pin Configuration
(All Pins Top View)

SSOP, TSSOP

1OEAB	1	56	1OEBA
1LEAB	2	55	1LEBA
1CEAB	3	54	1CEBA
GND	4	53	GND
1A1	5	52	1B1
1A2	6	51	1B2
V _{CC}	7	50	V _{CC}
1A3	8	49	1B3
1A4	9	48	1B4
1A5	10	47	1B5
GND	11	46	GND
1A6	12	45	1B6
1A7	13	44	1B7
1A8	14	43	1B8
2A1	15	42	2B1
2A2	16	41	2B2
2A3	17	40	2B3
GND	18	39	GND
2A4	19	38	2B4
2A5	20	37	2B5
2A6	21	36	2B6
V _{CC}	22	35	V _{CC}
2A7	23	34	2B7
2A8	24	33	2B8
GND	25	32	GND
2CEAB	26	31	2CEBA
2LEAB	27	30	2LEBA
2OEAB	28	29	2OEBA

Table 1. Pin Description

Name	Description
x \overline{OEAB}	A to B Output Enable Inputs (Active LOW)
x \overline{OEBA}	B to A Output Enable Inputs (Active LOW)
x \overline{CEAB}	A to B Enable Inputs (Active LOW)
x \overline{CEBA}	B to A Enable Inputs (Active LOW)
x \overline{LEAB}	A to B Latch Enable Inputs (Active LOW)
x \overline{LEBA}	B to A Latch Enable Inputs (Active LOW)
xAx	A to B Data Inputs or B to A 3-State Outputs (Bus Hold Inputs)
xBx	B to A Data Inputs or A to B 3-State Outputs (Bus Hold Inputs)

Table 2. Function Table

Inputs			Latch Status	Output Buffers
x \overline{CEAB}	x \overline{LEAB}	x \overline{OEAB}	xAx to xBx	xBx
H	X	X	Storing	High-Z
X	H	X	Storing	X
X	X	H	X	High-Z
L	L	L	Transparent	Current A Inputs
L	H	L	Storing	Previous* A Inputs

Notes:

- * = Before x \overline{LEAB} LOW-to-HIGH Transition
H = HIGH Voltage Level
L = LOW Voltage Level
X = Don't Care
- A-to-B data flow shown: B-to-A flow control is the same, except using x \overline{CEBA} , x \overline{LEBA} , x \overline{OEBA}

Table 3. Capacitance

Symbol	Pins	Typ	Unit	Conditions
C_{IN}	Input Capacitance	7.0	pF	$V_{IN} = 0V, V_{OUT} = 0V, f = 1MHz$
$C_{I/O}$	I/O Capacitance	8.0	pF	$V_{IN} = 0V, V_{OUT} = 0V, f = 1MHz$
C_{PD}	Power Dissipation Capacitance	25	pF	$V_{CC} = 3.3V, V_{IN} = 0 \text{ or } V_{CC}, f = 10MHz$

Note: Capacitance is characterized but not production tested.

Table 4. Absolute Maximum Ratings

Supply Voltage to Ground	-0.5V to 7.0V
DC Output Voltage V_{OUT}	
Outputs HIGH-Z	-0.5V to 7.0V
Outputs Active	-0.5V to $V_{CC} + 0.5V$
DC Input Voltage V_{IN}	-0.5V to 7.0V
DC Input Diode Current with $V_{IN} < 0$	-50mA
DC Output Diode Current	
$V_O < 0$	-50mA
$V_O > V_{CC}$	50mA
DC Output Source/Sink Current (I_{OH}/I_{OL})	$\pm 50mA$
DC Supply Current per Supply Pin	$\pm 100mA$
DC Ground Current per Ground Pin	$\pm 100mA$
T_{STG} Storage Temperature	-65° to 150°C

Note: Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to this device resulting in functional or reliability type failures.

Table 5. Recommended Operating Conditions

Symbol	Parameter		Min	Max	Unit
V_{CC}	Supply Voltage, Operating		2.0	3.6	V
	Supply Voltage, Data Retention Only		1.5	3.6	
V_{IN}	Input Voltage		0	5.5	V
V_{OUT}	Output Voltage in Active State		0	V_{CC}	V
	Output Voltage in "OFF" State		0	5.5	
I_{OH}/I_{OL}	Output Current	$V_{CC} = 3.0 - 3.6V$	—	± 12	mA
		$V_{CC} = 2.7V$	—	± 6	
$\Delta t/\Delta v$	Input Transition Slew Rate		—	10	ns/V
T_A	Operating Free Air Temperature		-40	85	°C

Table 6. DC Electrical Characteristics Over Operating RangeIndustrial Temperature Range, $T_A = -40^\circ\text{C}$ to 85°C

Symbol	Parameter	Test Conditions ⁽¹⁾	Min	Typ ⁽²⁾	Max	Unit
V_{IH}	Input HIGH Voltage	Logic HIGH for All Inputs	2.0	—	—	V
V_{IL}	Input LOW Voltage	Logic LOW for All Inputs	—	—	0.8	V
V_{OH}	Output HIGH Voltage	$V_{CC} = 2.7\text{V}$, $I_{OH} = -100\mu\text{A}$ $V_{CC} = 3.0\text{V}$, $I_{OH} = -12\text{mA}$ $V_{CC} = 3.0\text{V}$, $I_{OH} = -18\text{mA}$	$V_{CC} = 0.2$ 2.4 2.2	—	—	V
V_{OL}	Output LOW Voltage	$V_{CC} = 2.7\text{V}$, $I_{OL} = 100\mu\text{A}$ $V_{CC} = 3.0\text{V}$, $I_{OL} = 12\text{mA}$ $V_{CC} = 3.0\text{V}$, $I_{OL} = 18\text{mA}$	—	—	0.2 0.55 0.8	V
R_{OUT}	Output Resistance	$V_{CC} = 3.0\text{V}$, $I_{OL} = 12\text{mA}$	—	28	—	Ω
ΔV_T	Input Hysteresis ⁽³⁾	$V_{TLH} - V_{THL}$ for All Inputs	—	150	—	mV
I_I	Input Leakage Current	$V_I = 0\text{V}$, $V_I = 5.5\text{V}$	—	—	± 1.0	μA
$ I_{BH} $	Input Current	$V_{CC} = 3.6\text{V}$, $V_{IN} = 0\text{V}$ or $V_{IN} = V_{CC}$	—	—	50	μA
	Input High or Low Bus Hold Inputs ^(3,4)	$V_{CC} = 3.6\text{V}$, $0.8\text{V} < V_{IN} < 2.0\text{V}$	—	—	500 ⁽⁵⁾	μA
I_{BHH}	Bus Hold Sustaining Current	$V_{CC} = 3\text{V}$	-75	—	—	μA
I_{BHL}	Bus Hold Inputs	$V_{IN} = 0.8\text{V}$	75	—	—	μA
I_{OZ}	High-Z I/O Leakage ⁽³⁾	$V_O = 0\text{V}$, $V_O = 5.5\text{V}$ $V_I = V_{IH}$ or V_{IL}	—	—	± 1.0	μA
I_{OS}	Short Circuit Current ^(3,6)	$V_{CC} = 3.6\text{V}$, $V_O = \text{GND}$	-60	—	-200	mA
I_{OR}	Current Drive ⁽³⁾	$V_{CC} = 3.6\text{V}$, $V_{OUT} = 2.0\text{V}$	40	—	—	mA
I_{OFF}	Power Off Leakage	$V_{CC} = 0\text{V}$, V_I or $V_O = 5.5\text{V}$	—	—	10	μA
V_{IK}	Input Clamp Voltage	$V_{CC} = 2.7\text{V}$, $I_{IN} = -18\text{ mA}$	—	-0.7	-1.2	V

Notes:

- For conditions shown as Min. or Max. use appropriate value specified under Recommended Operation Conditions for the applicable device type.
- Typical values are at $V_{CC} = 3.3\text{V}$ and $T_A = 25^\circ\text{C}$.
- These parameters are guaranteed by characterization, but not production tested.
- Pins with Bus Hold are identified in the Pin Description.
- An external driver must provide at least $|I_{BH}|$ during transition to guarantee that the Bus Hold input will change state.
- Not more than one output should be tested at one time. Duration of test should not exceed one second.

Table 7. Power Supply Characteristics

Symbol	Parameter	Test Conditions ⁽¹⁾		Typ ⁽²⁾	Max	Unit
I _{CC}	Quiescent Power Supply Current	V _{CC} = 3.6V, Freq. = 0 V _{IN} = GND or V _{CC}		0.1	10	µA
ΔI _{CC}	Supply Current per Input @ TTL HIGH	V _{CC} = 3.6V, V _{IN} = V _{CC} - 0.6V ⁽³⁾	Control Inputs	2.0	30	µA
			Bus Hold Inputs	—	500	
I _{CCD}	Supply Current per Input per MHz ⁽⁴⁾	V _{CC} = 3.6V, Outputs Open One Bit Toggling @ 50% Duty Cycle xCEAB, xOEAB and xLEAB = GND	V _{IN} = V _{CC} V _{IN} = GND	65	100	µA/MHz
I _C	Total Power Supply Current ⁽⁶⁾	V _{CC} = 3.6V, Outputs Open One Bit Toggling @ 50% Duty Cycle f = 10MHz, xCEBA = V _{CC} xLEAB, xCEAB and xOEAB = GND	V _{IN} = V _{CC} - 0.6V V _{IN} = GND	0.5 ⁽⁵⁾	1.0 ⁽⁵⁾	mA
		V _{CC} = 3.6V, Outputs Open Sixteen Bits Toggling @ 50% Duty Cycle f = 2.5MHz, xCEBA = V _{CC} xLEAB, xCEAB and xOEAB = GND	V _{IN} = V _{CC} - 0.6V V _{IN} = GND	2.7 ⁽⁵⁾	8.0 ⁽⁵⁾	mA

Notes:

- For conditions shown as Min. or Max., use the appropriate values specified under Recommended Operating Conditions for applicable device type.
- Typical values are at V_{CC} = 3.3V, 25°C ambient.
- Per TTL driven input. All other inputs at V_{CC} or GND.
- This parameter is not directly testable, but is derived for use in total power supply calculations.
- Values for these conditions are examples of the I_{CC} formula. These limits are guaranteed by design but not tested.
- $I_C = I_{QUIESCENT} + I_{INPUTS} + I_{DYNAMIC}$.
 $I_C = I_{CCQ} + \Delta I_{CC} D_H N_T + I_{CCD} f N_O$.
 I_{CCQ} = Quiescent Current (I_{CCL}, I_{CCH}, and I_{CCZ}).
 ΔI_{CC} = Power Supply Current for a TTL-High Input (V_{IN} = V_{CC} - 0.6V).
 D_H = Duty Cycle for TTL High Inputs.
 N_T = Number of TTL High Inputs.
 I_{CCD} = Dynamic Current Caused by an Input Transition Pair (HLH or LHL).
 f = Average Switching Frequency per Output.
 N_O = Number of Outputs Switching.

Table 8. Dynamic Switching Characteristics⁽¹⁾

Symbol	Parameter	Conditions	V _{CC} (V)	T _A = 25°C		Units
				Typical		
V _{OLP}	Quiet Output Dynamic Peak V _{OL}	C _L = 30pF, V _{IH} = 3.3V, V _{IL} = 0V	3.3	0.8		V
V _{OLV}	Quiet Output Dynamic Valley V _{OL}	C _L = 30pF, V _{IH} = 3.3V, V _{IL} = 0V	3.3	0.8		V

Note:

- Characterized but not production tested.

Table 9. Switching Characteristics Over Operating RangeIndustrial Temperature Range, $T_A = -40^\circ\text{C}$ to 85°C . $C_{\text{LOAD}} = 30\text{pF}$, $R_{\text{LOAD}} = 500\Omega$ unless otherwise noted.

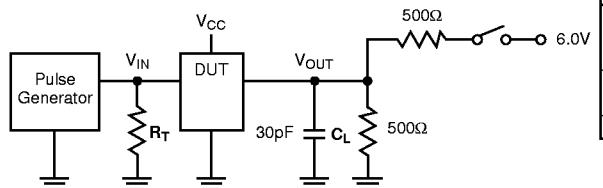
Symbol	Description ⁽¹⁾	$V_{\text{CC}} = 3.3 \pm 0.3\text{V}$		$V_{\text{CC}} = 2.7\text{V}^{(2)}$		Unit
		Min	Max	Min	Max	
t_{PHL} t_{PLH}	Propagation Delay Transparent Mode $x\text{Ax}$ to $x\text{Bx}$ or $x\text{Bx}$ to $x\text{Ax}$	1.5	6.0	1.5	7.0	ns
t_{PHL} t_{PLH}	Propagation Delay $x\text{LEBA}$ to $x\text{Ax}$, $x\text{LEAB}$ to $x\text{Bx}$	1.5	7.0	1.5	8.0	ns
t_{PZH} t_{PZL}	Output Enable Time $x\text{OEBA}$ or $x\text{OEAB}$ to $x\text{Ax}$ or $x\text{Bx}$, $x\text{CEBA}$ or $x\text{CEAB}$ to $x\text{Ax}$ or $x\text{Bx}$	1.5	8.0	1.5	9.0	ns
t_{PHZ} t_{PLZ}	Output Disable Time ⁽²⁾ $x\text{OEBA}$ or $x\text{OEAB}$ to $x\text{Ax}$ or $x\text{Bx}$, $x\text{CEBA}$ or $x\text{CEAB}$ to $x\text{Ax}$ or $x\text{Bx}$	1.5	6.5	1.5	7.5	ns
t_{SU}	Setup Time HIGH or LOW $x\text{Ax}$ or $x\text{Bx}$ to $x\text{LEBA}$ or $x\text{LEAB}$	2.0	—	2.0	—	ns
t_{H}	Hold Time HIGH or LOW $x\text{Ax}$ or $x\text{Bx}$ to $x\text{LEBA}$ or $x\text{LEAB}$	2.0	—	2.0	—	ns
t_{W}	Pulse Width LOW ⁽²⁾	5.0	—	5.0	—	ns
$t_{\text{SK(O)}}$	Output Skew ⁽³⁾	—	0.5	—	—	ns

Notes:

1. Minimums guaranteed but not tested. See Test Circuit and Waveforms.
2. Guaranteed by characterization.
3. Skew between any two outputs of the same package switching in the same direction.
This parameter is guaranteed by characterization but not production tested.

TEST CIRCUIT AND WAVEFORMS

Figure 3. Test Circuit



SWITCH POSITION

Test	Switch
Open Drain	6V
Disable LOW	
Enable LOW	
Disable HIGH	GND
Enable HIGH	
All Other Inputs	Open

DEFINITIONS:

C_L = Load capacitance: includes jig and probe capacitance.

R_T = Termination resistance: should be equal to Z_{OUT} of the Pulse generator.

Figure 4. Setup, Hold, and Release Timing

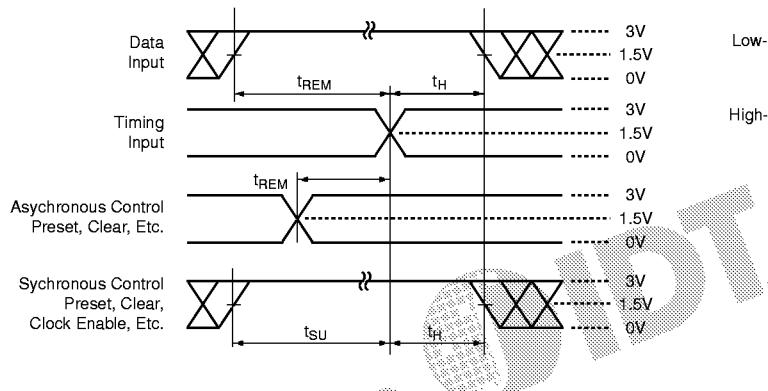


Figure 6. Pulse Width

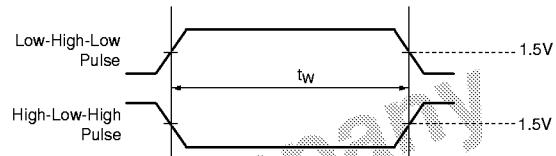


Figure 5. Enable and Disable Timing

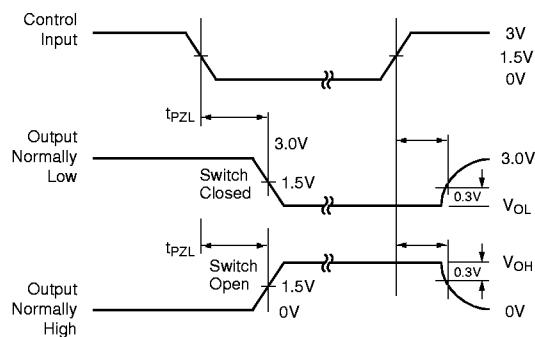
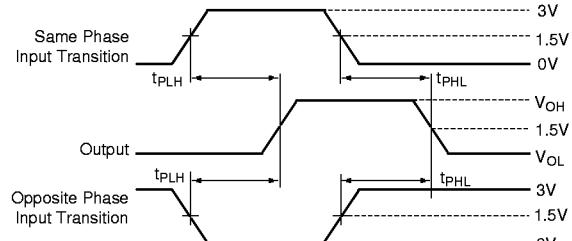


Figure 7. Propagation Delay



Notes:

1. Input Control Enable = LOW and Input Control Disable = HIGH.
2. Pulse Generator for All Pulses: Rate $\leq 1.0\text{MHz}$;
 $Z_{\text{OUT}} \leq 50\Omega$; $t_F, t_R \leq 2.5\text{ns}$.